

# United States Patent [19]

Hirose et al.

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[54]	TURN	ITH POL	S INCLUDI ISHING SI IS	
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[51] Int. Cl.<sup>6</sup> ...... B24B 29/02 

[58] Field of Search ...... 451/41, 293, 285,

451/287, 288, 289, 290, 495, 520, 527, 528, 530

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#### **ABSTRACT** [57]

A polishing apparatus includes a turntable with an abrasive cloth mounted on an upper surface thereof, and a top ring disposed above the turntable for supporting a workpiece to be polished and pressing the workpiece against the abrasive cloth under a predetermined pressure. The turntable and the top ring are movable relatively to each other to polish a surface of the workpiece supported by the top ring with the abrasive cloth. The abrasive cloth has a projecting region on a surface thereof for more intensive contact with the workpiece than other surface regions of the abrasive cloth. The projecting region has a smaller dimension in a radial direction of the turntable than a diameter of the workpiece when the projecting region is held in contact with the workpiece. A position of the projecting region is determined on the basis of an area in which the projecting region acts on the workpiece.

#### 21 Claims, 21 Drawing Sheets

